

# **NCE N-Channel Super Trench II Power MOSFET**

#### **Description**

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{\text{DS(ON)}}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

## **Application**

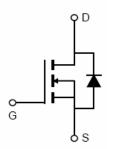
- DC/DC Converter
- ●Ideal for high-frequency switching and synchronous rectification

#### **General Features**

- $V_{DS}$  =72V, $I_D$  =140A  $R_{DS(ON)}$ =3.3m $\Omega$  , typical @  $V_{GS}$ =10V
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!





**Schematic Diagram** 

## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP035N72	NCEP035N72	TO-220	-	-	-

## Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	72	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	140	Α
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	108	Α
Pulsed Drain Current	I <sub>DM</sub>	560	Α
Maximum Power Dissipation	P <sub>D</sub>	190	W
Derating factor		1.27	W/℃
Single pulse avalanche energy (Note 5)	Eas	870	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	$^{\circ}$

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>eJC</sub>	0.79	°C/W
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Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

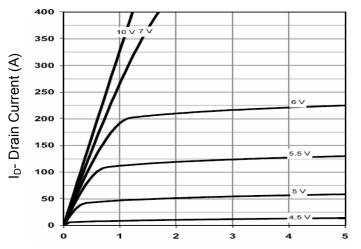
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	72		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =72V,V <sub>GS</sub> =0V	-	-	1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	<u> </u>		•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =70A	-	3.3	3.5	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =70A	75	-	-	S
Dynamic Characteristics (Note4)	<u> </u>		•			
Input Capacitance	C <sub>lss</sub>	)/ 05)/// 0)/	-	4250	-	PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =35V, $V_{GS}$ =0V,	-	670	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	28	-	PF
Switching Characteristics (Note 4)	<u> </u>		•			
Turn-on Delay Time	t <sub>d(on)</sub>		-	16	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 35V, I_{D} = 70A$	-	10	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =1.6 $\Omega$	-	35	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	8	-	nS
Total Gate Charge	Qg	\/ 05\/1 704	-	67.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =35V, $I_D$ =70A, $V_{GS}$ =10V	-	18.8		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V	-	13.5		nC
Drain-Source Diode Characteristics	<u> </u>			l.	l.	
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =70A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	140	Α
Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25^{\circ}C, I_F = 70A$	-	68	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	98	-	nC

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production

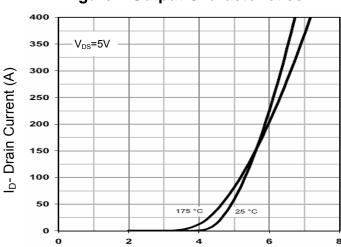


## **Typical Electrical and Thermal Characteristics**



Vds Drain-Source Voltage (V)

**Figure 1 Output Characteristics** 



Vgs Gate-Source Voltage (V)

**Figure 2 Transfer Characteristics** 

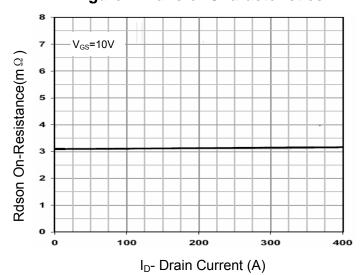
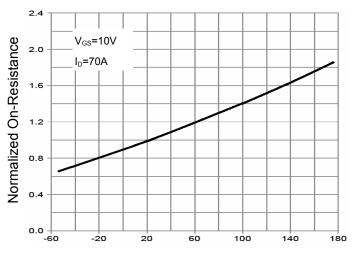
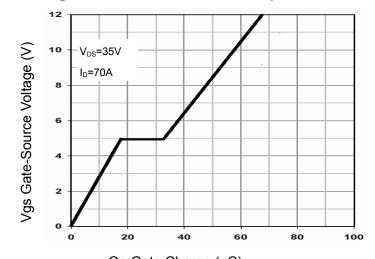


Figure 3 Rdson- Drain Current



T<sub>J</sub>-Junction Temperature(°C)

**Figure 4 Rdson-Junction Temperature** 



Qg Gate Charge (nC)

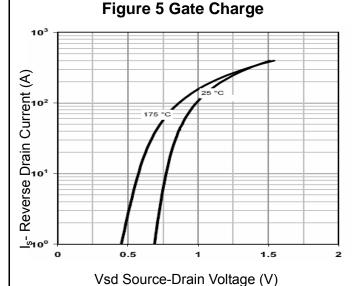
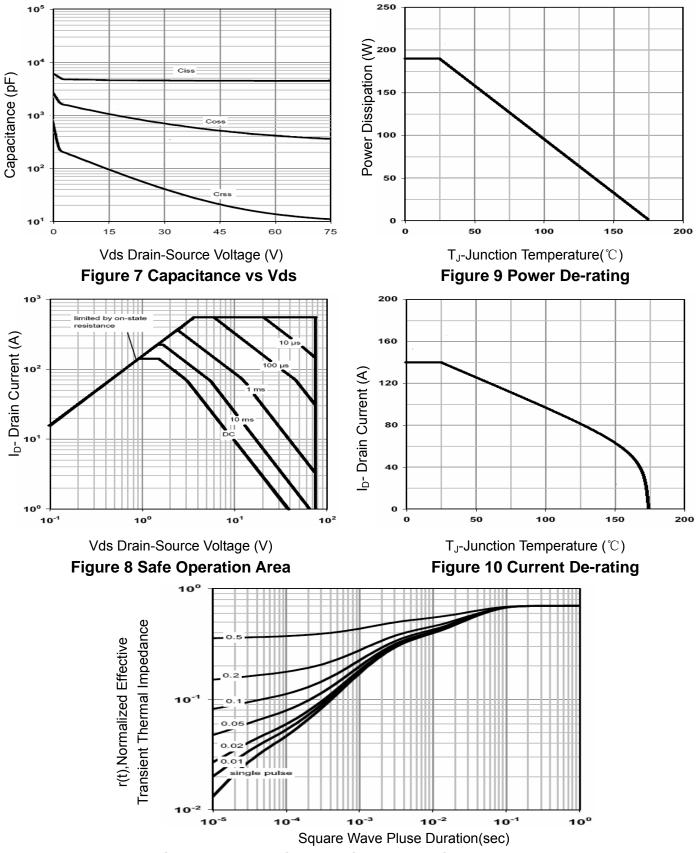


Figure 6 Source- Drain Diode Forward

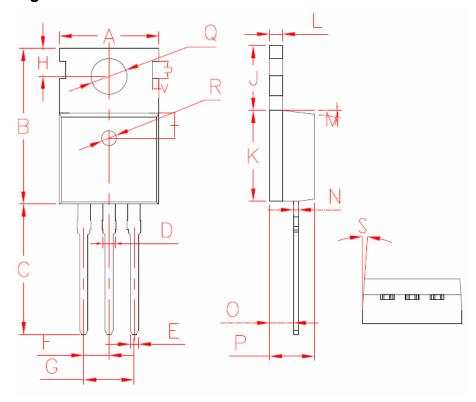




**Figure 11 Normalized Maximum Transient Thermal Impedance** 



# **TO-220-3L Package Information**



Symbol	Min	Non	Max	
A	9.80	10.00	10.20	
В	15.40	15.60	15.80	
С	12.75	13.10	13.45	
D	1.18	1.31	1.44	
E	0.70	0.80	0.90	
F	2.42	2.54	2.66	
G	4.84	5.08	5.32	
Н	2.73	2.80	2.87	
I	2.40	2.50	2.60	
J	6.40	6.50	6.60	
K	9.00	9.10	9.20	
L	1.29	1.30	1.32	
M	6.5°	7.0°	7.5°	
N	0.48	0.50	0.56	
0	2.35	2.4	2.5	
P	4.4	4.5	4.7	
Q	3.5	3.6	3.63	
R	1.4	1.5	1.6	
S	2°	2.5°	3°	
U	1.65	1.75	1.85	
V	0.58	0.68	0.78	



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